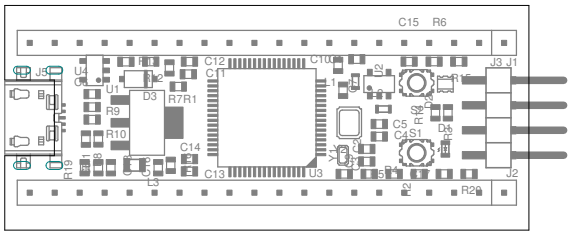
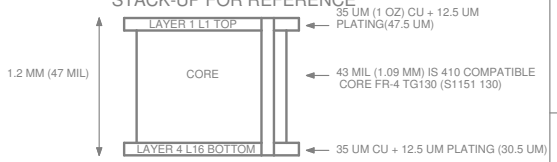


LAYER-STACK

Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	170	YES
×	2	31	0.80	4	YES
◻	3	40	1.02	44	YES

STACK-UP FOR REFERENCE



NOTES:

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TG 130 EPOXY LAMINATE WITH 35 UM COPPER PLATING AND 1.2 MM THICKNESS.

2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE.

3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.

4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.

5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.

6. BOARD TO HAVE BLUE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
EQUIVALENT WET OR DRY FILM MAY BE USED.

7. SILKSCREEN BOARD USING WHITE INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE.

8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:

* 2 COPPER LAYERS
* 1.2 MM BOARD THICKNESS
* REQUIRES TOP AND BOTTOM SIDE SILKSCREENS

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BluePillF4

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Component Assembly CMP (.ASC) | Rev. A